LEOCO CORPORATION PRODUCTION SPECIFICATION No. S-96-5080 REV 3

* 5080 Series and 5086 Series Connector *

This product specification contains the test method, the general performance and requirements for interconntection system connector with 5080 series socket ,5086 series header and 3973 \, 3978 \, 3983 series crimp terminal.

1. Construction and dimensions shall be in accordance with the referenced drawings.

产品结构和尺寸依据所提供的产品图面.

2. Characteristics 特性:

Current rating 额定电流: 5A AC,DC Voltage rating 额定电压: 250V AC,DC Temperature rating 额定温度: -25℃ ~ +105℃

Applicable wire 适用线材: conductor construction size #18 ~ #24

3. Electrical performance 电气特性:

ITEM	DESCRIPTION	TEST METHOD & CONDITION	REQUIREMENT				
	内容	测试方法与条件	需 求				
3-1	Contact Resistance	It should be tested in accordance with	Initial: 20 m Ω max.				
	接触阻抗	method EIA-364-23	After environmental				
			Test: 40 m Ω max.				
3-2	Insulation	It should be tested in accordance with	Initial: $1000 M\Omega$ min.				
	Resistance	Method EIA-364-21	After humidity test				
	绝缘阻抗		500 M Ω min.				
3-3	Dielectric	Unmated connectors shall be tested in	No evidence of break-				
	Withstanding	Accordance with method EIA-364-20	Down and flashover				
	Voltage	When the AC 1500 V rms for one minute					
	耐电压	applied between adjacent contacts.					
4. Mechanical Performance 机械特性:							

	voltago	Whom the receivement on the minute						
	耐电压	applied between adjacent contacts.						
4. Mechanical Performance 机械特性:								
ITEM	DESCRIPTION	TEST METHOD & CONDITION	REQUIREMENT					
	内容	测试方法与条件	需求					
4-1	Crimp	Pulling load shall be applied between	AWG #18: 10.0 kgf min.					
	Tensile	Correctly crimped contact and wire at a	AWG #20: 6.0 kgf min.					
	Strength	constant speed. Pulling speed: 25 mm /	AWG #22:4.0 kgf min.					
	铆合张力强度	minute.	AWG #24: 2.5 kgf min.					
4-2	Contact Insertion	The force required to insert a contact	1.25kgf max.					
	Force	into a housing. Inserting speed:						
	接触插入力	25 mm / minute.						
4-3	Contact removal	Crimped contact mounted in a housing	2.0 Kgf min.					
	Force	shall be pulled in an alignment at a						
	接触拨出力	constant speed of 25 mm / minute.						
4-4	Post retention force	The end of a post shall be pushed in a	2.0 kgf min					
	保持力	perpendicular to base housing at a						
		constant speed of 25mm/minute						
4-5	Insertion Force	Housing with contact mating header at a	2.0 kgf min					
	插入力	constant speed of 25 mm / minute.						
4-6	Withdrawal Force	Housing with contact mating header, Pull	0.5 kgf max					
	拨出力	out from header at speed 25 mm /						
	The state of the s	minute.						
4-7	Durability	It should be tested in accordance with	No defects.					
	耐久力	method EIA-364-09	Contact resistance shall be					
		Connector shall be subjected to 100	20m $Ω$ max					
		cycles of insertion and withdrawal						

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ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	·	REQUIREMENT 需 求							
4-8		The connector mated PCB shall be vibrated in accordance with method EIA-364-28. There shall be no current discontinuity longer than 1 microsecond during the te Frequency: 10-55-10 Hz / min. Amplitude: 1.52mm Period: 2 hours for each direction	est .	No evidence of loosening of parts or electric discontinuity. Contact resistance less than twice of initial.		С					
5. Environmental Performance 环境特性:											
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件		REQUIREMENT 需 求							
5-1	Humidity 耐湿性	The unmated connector shall be tested accordance with method EIA-364-31. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours.	I	NO damage. Contact resista Than twice of i nsulation resist to paragraph 3 Dielectric withst voltage: to para	nitial. ance: -2. and ing	g					
5-2	Salt Spray 盐雾试验	Connector shall be tested in accordance with method EIA-364-26 Temperature: 35±2 °C Density: 5 % in weight. Period: 16 hours.		NO damage. Contact resista than twice of ir	ınce le						
5-3	Solderability 着锡性	Connector termination ends shall be checked for solderability in accordance with method EIA-364-252 Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.	÷	NO damage. Minimum: 95 % immersed area							
5-4	Resistance to Soldering Heat 附着耐热性	Specimen shall be mounted on PCB. Solder temperature: 260±5 °C Immersion period: 5±0.5 sec.		NO damage ar deformation.	nd						
APPR BY: TONY 02/11'14		CHKD BY: CHARD 02/11'14	SPEC	PEC BY:SMILE 02/11'14							

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